

SOT819-1

plastic thermal enhanced low profile land grid array package;
28 lands; resin based; body 6 x 6 x 1.4 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HLLGA28R
Package type industry code	HLLGA28R
Package style descriptive code	HLLGA (thermal enhanced low profile land grid array)
Package style suffix code	R (resin based)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-11-2007

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		5.9	-	6	6.1	mm
E	package width		5.9	-	6	6.1	mm
A	seated height		[tbd]	-	1.4	1.4	mm
A ₂	package height		[tbd]	-	1.4	[tbd]	mm
n ₂	actual quantity of termination		-	-	28	-	



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x 1.4 mm

2. Package outline

HLLGA28R: plastic thermal enhanced low profile land grid array package;
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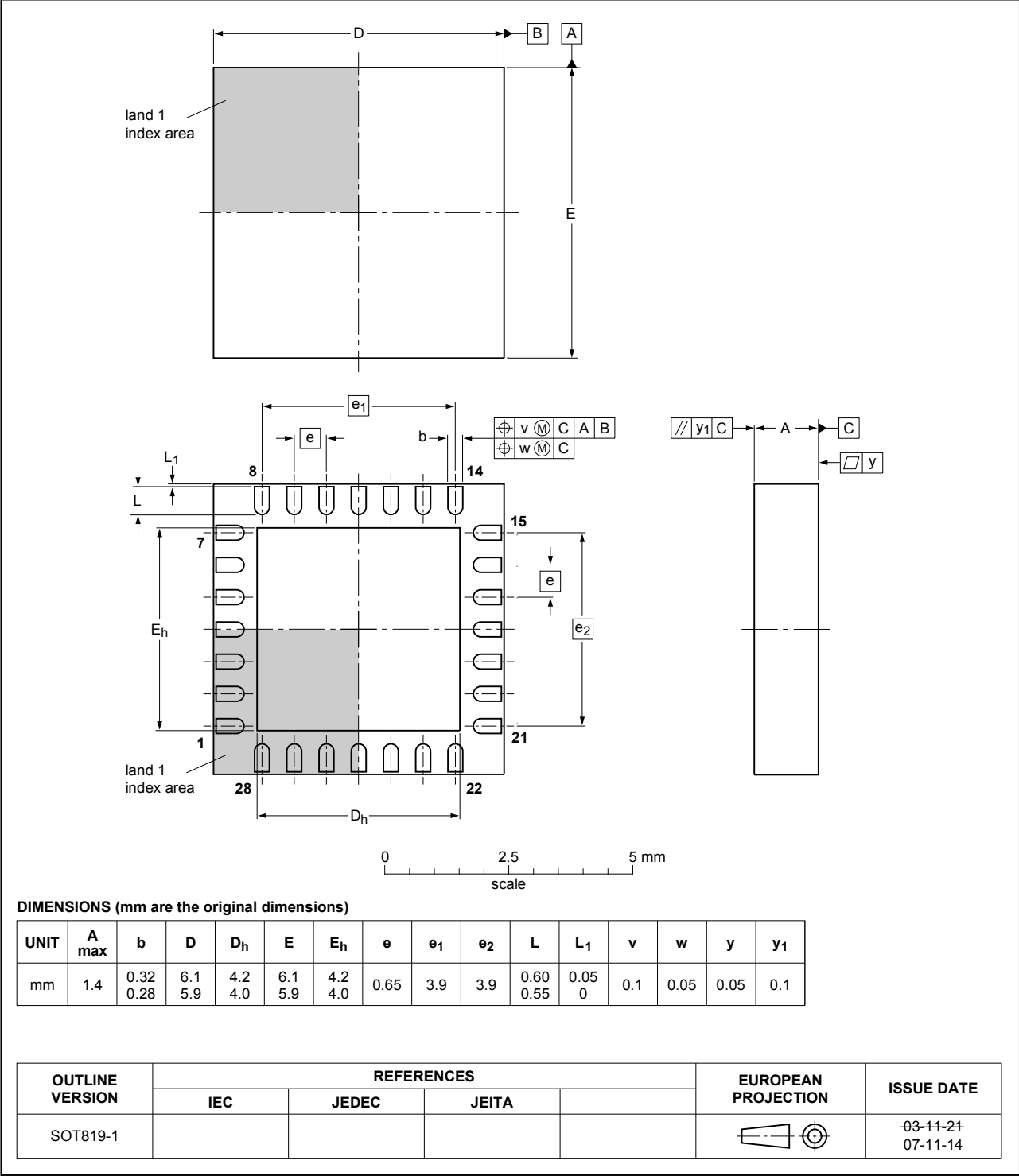


Fig. 1. Package outline HLLGA28R (SOT819-1)

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3. Legal information

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